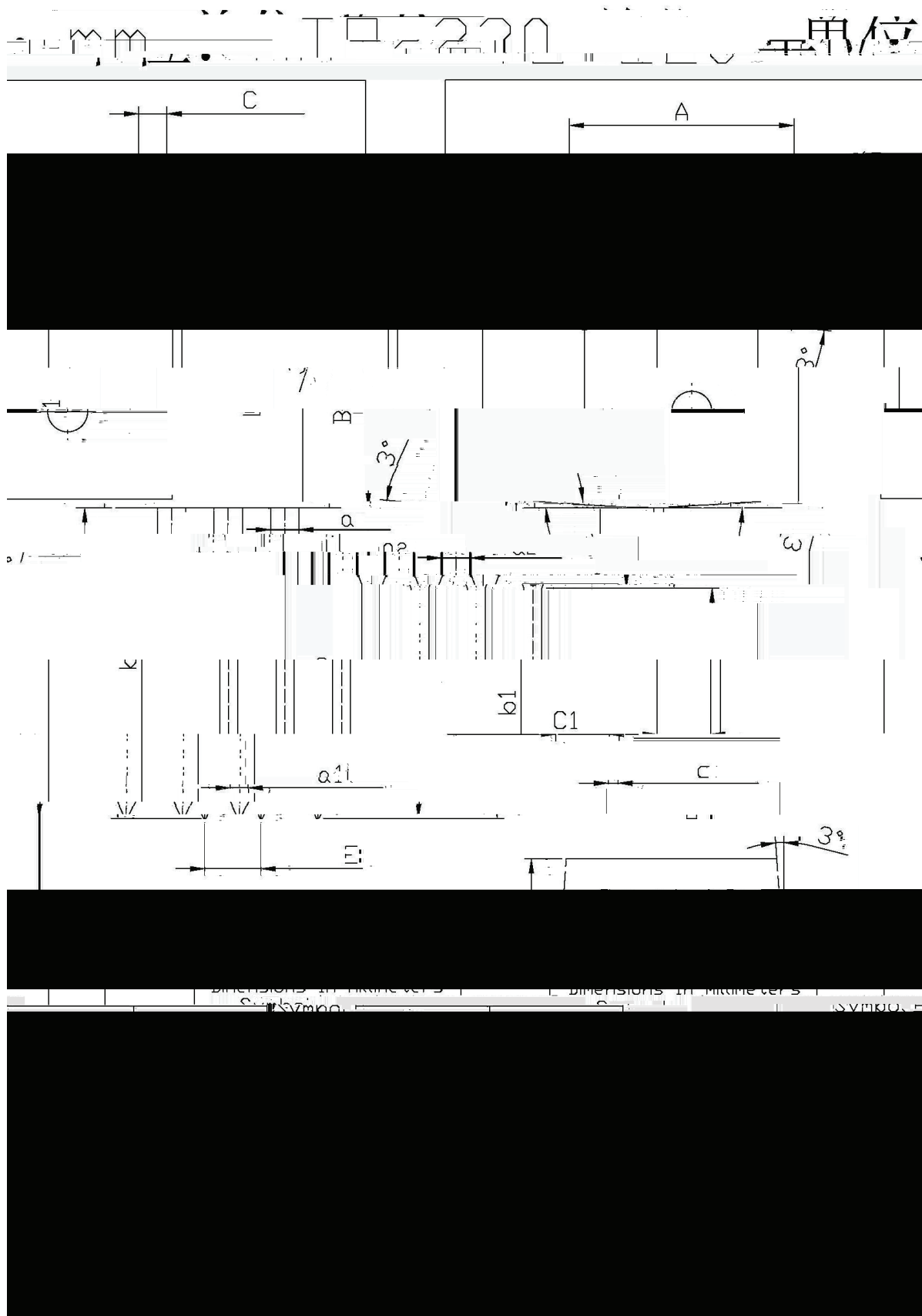


Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-60	V
Collector to Emitter Voltage	V_{CEO}	-50	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-5.0	A
Collector Power Dissipation	P_C	2.0	W
	$P_C(T_C=25^\circ\text{C})$	25	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

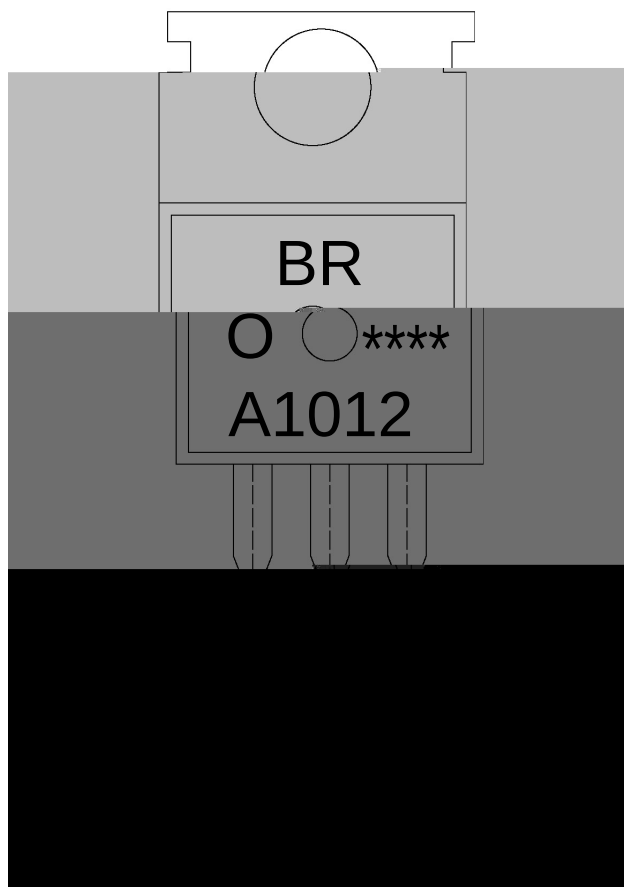
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage	V_{CE0}	$I_C=10\mu A, T_C=25^\circ C$				V
DC Current Gain	β_{DC}	$I_C=10\mu A, V_{CE}=10V, T_C=25^\circ C$				
Small Signal AC Current Gain	β_{AC}	$I_C=10\mu A, V_{CE}=10V, T_C=25^\circ C, f=1kHz$				
Transition Frequency	f_T	$I_C=10\mu A, V_{CE}=10V, T_C=25^\circ C$				Hz
Output Resistance	r_o	$I_C=10\mu A, V_{CE}=10V, T_C=25^\circ C$				Ω



/ Package Dimensions



/ Marking Instructions



BR

A1012

O: h_{FE}

Note:

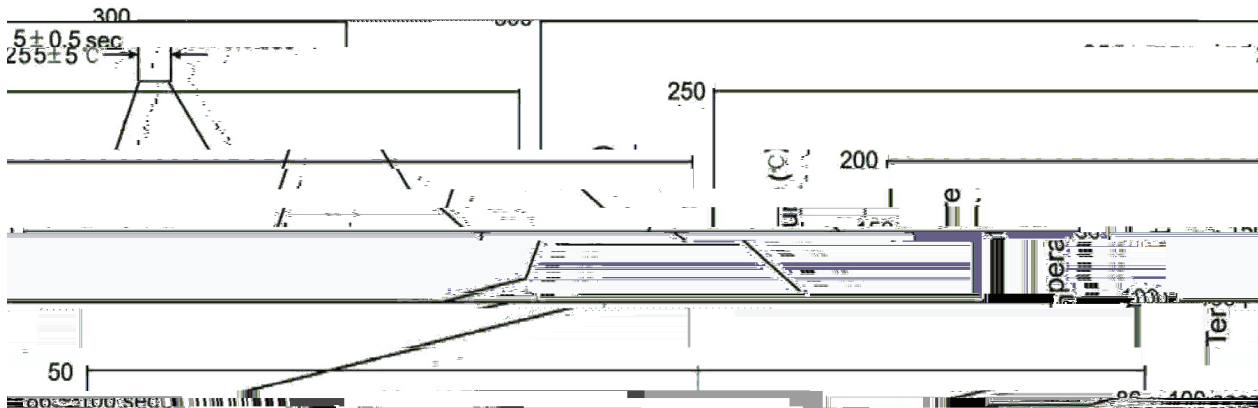
BR: Company Code

A1012: Product Type.

O: h_{FE} Classifications Symbol

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255±5 | | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270±5 10±1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units		Dimension		(unit mm ³)
	Units/Bag	Bags/Inner Box	Units/Inner Box	Length	Width
	/	/	/	mm	mm